

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT
(Under 37 CFR 1.97(b) or 1.97(c))

Docket No.
SEC.689

In Re Application Of: Chan Hoon Park et al.

Patent No.
09/484,051

Filing Date
01/18/00

Examiner
ATKINSON, C

Group Art Unit
3743

Title: **WAFER HEATING APPARATUS HAVING FLUID HEAT TRANSFER MEDIUM AND METHOD
OF HEATING A WAFER USING THE SAME**

Address to:
Assistant Commissioner for Patents
Washington, D.C. 20231

37 CFR 1.97(b)

1. ☒ The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application; within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; or before the mailing date of a first Office Action on the merits, whichever event occurs last.

37 CFR 1.97(c)

2. ☐ The Information Disclosure Statement submitted herewith is being filed after three months of the filing of a national application, or the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; or after the mailing date of a first Office Action on the merits, whichever occurred last but before the mailing date of either:

1. a Final Action under 37 CFR 1.113, or
2. a Notice of Allowance under 37 CFR 1.311,

whichever occurs first.

Also submitted herewith is:

- ☐ a certification as specified in 37 CFR 1.97(e);

OR

- ☐ the fee set forth in 37 CFR 1.17(p) for submission of an Information Disclosure Statement under 37 CFR 1.97(c).

3. ☒ Also enclosed are (a) a copy of an April 13, 2001, Notice To Submit Response which issued by the Korean Patent Office in connection with the Korean priority application, and (b) an English-language translation of said Notice.

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Payment of Fee

(Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))

- ☐ A check in the amount of _____ is attached.
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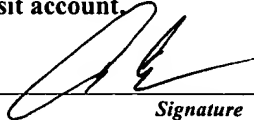
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Dated: JUNE 26, 2001


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